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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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High Efficiency Thyristor

1200 V

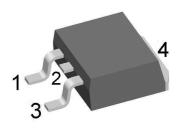
20 A

1.31 V

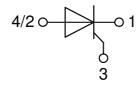
Single Thyristor

Part number

CS19-12ho1S



Backside: anode



Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: TO-263 (D2Pak)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

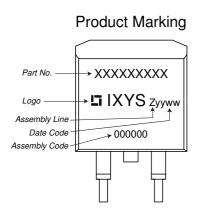
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Cymab - I	Pofinition	Conditions		me!	Ratings		11
Symbol	Definition	Conditions	$T_{VJ} = 25^{\circ}C$	min.	typ.	max. 1300	Un
V _{RSM/DSM}	max. non-repetitive reverse/forwa						į.
V _{RRM/DRM}	max. repetitive reverse/forward bl		$T_{VJ} = 25^{\circ}C$			1200	! '
I _{R/D}	reverse current, drain current	$V_{R/D} = 1200 \text{ V}$	$T_{VJ} = 25^{\circ}C$			50	μ
		$V_{R/D} = 1200 \text{ V}$	$T_{VJ} = 125$ °C			1	m
V_{T}	forward voltage drop	$I_T = 20 A$	$T_{VJ} = 25^{\circ}C$			1.32	,
		$I_T = 40 \text{ A}$				1.65	'
		$I_T = 20 A$	$T_{VJ} = 125$ °C			1.31	,
		$I_T = 40 \text{ A}$				1.73	'
I _{TAV}	average forward current	$T_C = 110$ °C	$T_{VJ} = 125$ °C			20	
T(RMS)	RMS forward current	180° sine				31	
V _{T0}	threshold voltage		T _{vJ} = 125°C			0.86	1
r _T	slope resistance	oss calculation only				22	m!
R _{thJC}	thermal resistance junction to cas	e				0.7	K/V
R _{thCH}	thermal resistance case to heatsing	nk			0.50		K/V
P _{tot}	total power dissipation		T _C = 25°C			170	٧
I _{TSM}	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			180	
TOM		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			195	
		t = 10 ms; (50 Hz), sine	T _{v.i} = 125°C			155	
		t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			165	
l²t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			160	1
	value is: ideniig	t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			160	A ²
		t = 0.5 ms; (50 Hz), sine	$T_{VJ} = 125$ °C			120	A ²
		t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			115	A ²
<u> </u>	junction capacitance	$V_R = 230 \text{ V} f = 1 \text{ MHz}$	$V_R = 0 V$ $T_{VJ} = 25^{\circ}C$		9	113	pl
C _J			$T_{\rm VJ} = 25 \rm C$ $T_{\rm C} = 125 \rm ^{\circ} C$		9	E	V
P_{GM}	max. gate power dissipation	$t_P = 30 \mu s$	1 _C = 125 °C			5	ļ .
_		$t_{P} = 300 \mu s$				2.5	۷
P _{GAV}	average gate power dissipation					0.5	۷
(di/dt) _{cr}	critical rate of rise of current	$T_{VJ} = 150 ^{\circ}\text{C}; f = 50 \text{Hz}$ re	•			150	A/μ
		$t_P = 200 \mu s; di_G/dt = 0.15 A/\mu s; -$					
			on-repet., $I_T = 20 A$				A /μ
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150$ °C			500	V/µ
		R _{GK} = ∞; method 1 (linear volta	ge rise)				1 1 1 1
V_{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			1.5	١
			$T_{VJ} = -40$ °C			2.5	١
I _{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			28	m
			$T_{VJ} = -40$ °C			50	m/
V _{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150^{\circ}C$			0.2	١
I _{GD}	gate non-trigger current					3	m/
IL	latching current	t _p = 10 μs	$T_{VJ} = 25$ °C			75	m
•L	-	$I_{G} = 0.1 \text{ A}; \text{ di}_{G}/\text{dt} = 0.1 \text{ A}/\mu \text{s}$					1 1 1
I _H	holding current	$V_{D} = 6 \text{ V } R_{GK} = \infty$	$T_{VJ} = 25$ °C			50	m
тн t _{gd}	gate controlled delay time	$V_{D} = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25 ^{\circ}\text{C}$			2	i
∙ gd	gate controlled delay tillle	$I_{G} = 0.1 \text{ A}; \text{ di}_{G}/\text{dt} = 0.1 \text{ A}/\mu\text{s}$					μ
		$I_G = U.IA$, $UI_G/UI = U.IA/\mu$					ļ.
t _q	turn-off time	$V_{R} = 100 \text{ V}; I_{T} = 20 \text{ A}; V = \frac{2}{3}$	/ \/ T 400.00		150		μ



Package	Package TO-263 (D2Pak)			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
I _{RMS}	RMS current	per terminal			35	Α	
T _{VJ}	virtual junction temperature		-40		125	°C	
T _{op}	operation temperature		-40		100	°C	
T _{stg}	storage temperature		-40		150	°C	
Weight				2		g	
F _c	mounting force with clip		20	1	60	N	



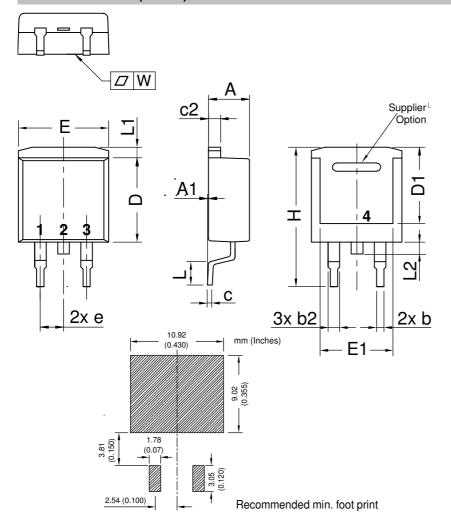
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CS19-12ho1S	CS19-12ho1S	Tape & Reel	800	501313
Alternative	CS19-12ho1S-TUB	CS19-12ho1S	Tube	50	473340

Similar Part	Package	Voltage class
CS19-12ho1	TO-220AB (3)	1200
CS19-08ho1	TO-220AB (3)	800
CS19-08ho1S	TO-263AB (D2Pak) (2)	800

Equiva	alent Circuits for	Simulation	* on die level	T _{VJ} = 125 °C
$I \rightarrow V_0$)—[R ₀]-	Thyristor		
V _{0 max}	threshold voltage	0.86		V
$R_{0 \text{ max}}$	slope resistance *	19		mΩ

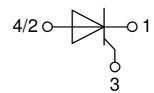


Outlines TO-263 (D2Pak)



	Millir	neter	Inc	hes	
Dim.	min	max	min	max	
Α	4.06	4.83	0.160	0.190	
A1	typ.	typ. 0.10		0.004	
A2	2.41		0.095		
b	0.51	0.99	0.020	0.039	
b2	1.14	1.40	0.045	0.055	
С	0.40	0.74	0.016	0.029	
c2	1.14	1.40	0.045	0.055	
D	8.38	9.40	0.330	0.370	
D1	8.00	8.89	0.315	0.350	
D2	2.5		0.098		
Е	9.65	10.41	0.380	0.410	
E1	6.22	8.50	0.245	0.335	
е	2,54 BSC		0,100 BSC		
e1	4.28		0.169		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	1.02	1.68	0.040	0.066	
W	typ. 0.02	0.040	typ. 0.0008	0.002	

All dimensions conform with and/or within JEDEC standard.





Thyristor

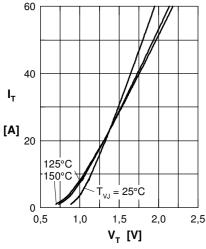


Fig. 1 Forward characteristics

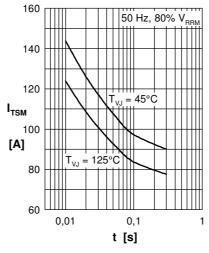


Fig. 2 Surge overload current

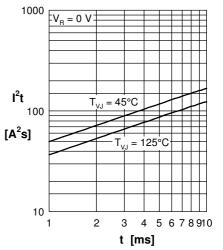


Fig. 3 I²t versus time (1-10 ms)

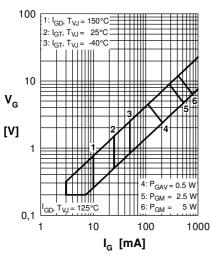


Fig. 4 Gate trigger characteristics

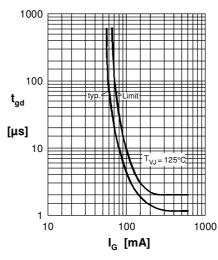


Fig. 5 Gate controlled delay time

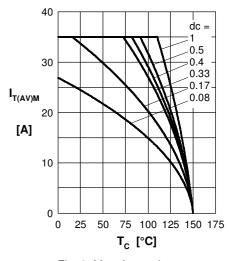


Fig. 6 Max. forward current at case temperature

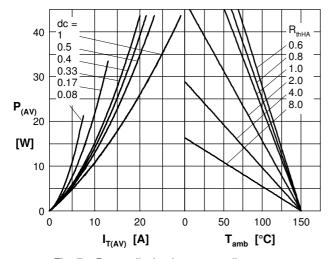


Fig. 7a Power dissipation versus direct output current Fig. 7b and ambient temperature

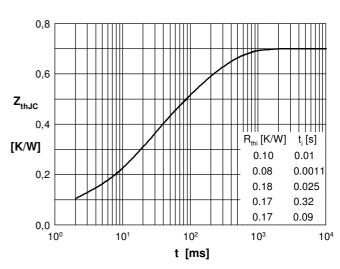


Fig. 8 Transient thermal impedance junction to case